IPC-2152

Standard for Determining Current Carrying Capacity in Printed Board Design

August 2009

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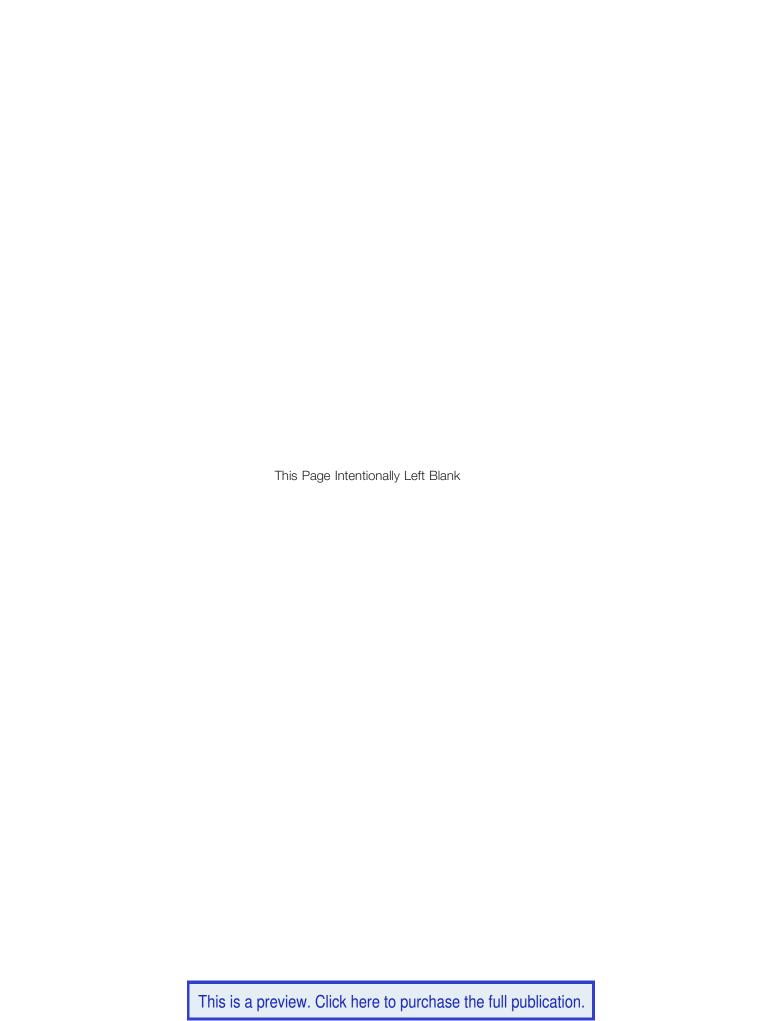
Developed by the Current Carrying Capacity Task Group (1-10b) of the Printed Board Design Committee (1-10) of IPC

Users of this standard are encouraged to participate in the development of future revisions.

Contact:

IPC 3000 Lakeside Drive, Suite 309S Bannockburn, Illinois 60015-1249 Tel 847 615.7100 Fax 847 615.7105

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Printed Board Design Committee	Current Carrying Capacity Task Group	Technical Liaisons of the IPC Board of Directors
Chair	Chair	
Lionel Fullwood	Michael Jouppi	Peter Bigelow
WKK Distribution Ltd.	Lockheed Martin	IMI Inc.
Vice Chair		Sammy Yi
Gary Ferrari		Aptina Imaging Corporation
FTG Circuits		

Current Carrying Capacity Task Group

Byron Case, L-3 Communications Phillip Chen, L-3 Communications Electronic Systems David Corbett, Defense Supply	Lionel Fullwood, WKK Distribution Ltd. Michael Green, Lockheed Martin Space Systems Company	Michael Miller, NSWC Crane Tim Minko, Coretec Inc. Gary Morgan, Ball Aerospace & Technologies
Center Columbus William Dieffenbacher, BAE Systems Platform Solutions C. Don Dupriest, Lockheed Martin Missiles and Fire Control	Christopher Katzko, Shanghai Meadville Electronics Co. Ltd. Donald Kyle, Schlumberger Well Services Jim Long, ITT Power Solutions	Jack Olson, Caterpillar Inc. William Ortloff, Raytheon Company Karl Sauter, Sun Microsystems Inc. Dewey Whittaker, Honeywell Inc. Air Transport Systems
Gary Ferrari, FTG Circuits	Kenneth Manning, Raytheon Company	John Williams, Raytheon Company

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Missiles and Fire Control
Michael Green, Lockheed Martin
Space Systems Company

Michael Jouppi, Lockheed Martin Jack Olson, Caterpillar Inc. Michael Miller, NSWC Crane

Brian Strandjord, Thermal Management, Inc.

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Standard for Determining Current Carrying Capacity in Printed Board Design

1 SCOPE

This document is intended as a general guide to understanding the relationship between current, conductor size, and temperature, and can be used more specifically in the design and evaluation of copper conductors in printed boards (PBs).

- **1.1 Purpose** The purpose of this document is to provide guidance on determining the appropriate conductor sizes on the finished PB as a function of the current carrying capacity required and the acceptable conductor temperature rise.
- **1.2 Presentation** All dimensions and tolerances in this standard are expressed in hard SI (metric) units and parenthetical soft imperial (inch) units. Users of this standard are expected to use metric dimensions.
- **1.3 Interpretation** "**Shall**," the imperative form of the verb, is used throughout this standard whenever a requirement is intended to express a provision that is mandatory. Deviation from a "**shall**" requirement may be considered if sufficient data is supplied to justify the exception.

The words "should" and "may" are used whenever it is necessary to express non-mandatory provisions.

"Will" is used to express a declaration of purpose.

To assist the reader, the word "shall" is presented in bold characters.

- **1.4 Definition of Terms** The definition of all terms used herein **shall** be in accordance with IPC-T-50 and as defined in 1.4.1 through 1.4.13.
- **1.4.1 Ambient** The surrounding environment coming into contact with the system or component in question.
- **1.4.2 Base Material** The insulating material upon which a conductive pattern may be formed (The base material may be rigid or flexible or both. It may be a dielectric or insulated metal sheet).
- **1.4.3 Circuitry Layer** A layer of PB containing conductors, including ground and voltage planes.
- **1.4.4 Conductive Pattern** The configuration or design of the conductive material on a base material. (This includes conductors, lands, vias, planes, and passive components when these are an integral part of the PB manufacturing process.)
- **1.4.5 Conductor Spacing** The observable distance between adjacent edges (not center-to-center spacing) of isolated conductive patterns in a conductor layer.
- **1.4.6 Conductor Thickness** Thickness of a conductor including additional metallic coatings but excluding non-conductive coatings.
- **1.4.7 Conductor Width** The observable width of a conductor at any point chosen at random on a PB as viewed from directly above unless otherwise specified.
- **1.4.8 Convection** Heat transfer that occurs at the interface of a solid and a fluid or gas that is due to their differences in temperature.
- **1.4.9 Copper Weight** The mass of copper per unit area for a foil, typically expressed in ounces per square foot or grams per square centimeter (these units are not equivalent).
- **1.4.10 Current-Carrying Capacity** The maximum electrical current that can be carried continuously by a conductor, without causing an objectionable degradation of electrical or mechanical properties of the product.